

S/N 09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 08, 2000	Docket:	884.798US1
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		
Assignee:	Intel Corporation	Customer No:	21186

INFORMATION DISCLOSURE STATEMENT

MS RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

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Serial No : 09/733,289

Filing Date: December 08, 2000

Title: Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers

Assignee: Intel Corporation

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The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

XIAO-CHUN MU ET AL.

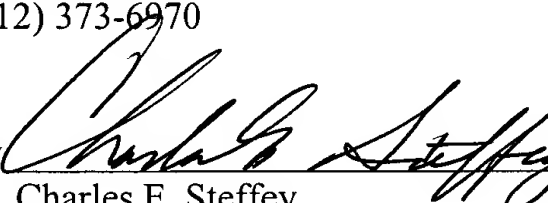
By their Representatives,

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Minneapolis, Minnesota 55402
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Date

January 4, 2005

By



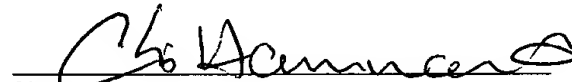
Charles E. Steffey
Reg. No. 25,179

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS RCE, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 4 day of January, 2005.

Name

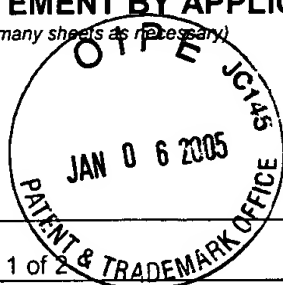
Chris Hammond

Signature



Substitute for form 1449A/PTO
**INFORMATION DISCLOSURE
 STATEMENT BY APPLICANT**

(Use as many sheets as necessary)



Complete if Known

Application Number	09/733,289
Filing Date	December 8, 2000
First Named Inventor	Mu, Xiao-Chun
Group Art Unit	2814
Examiner Name	Nguyen, DiLinh

Sheet 1 of 2

Attorney Docket No: 884.798US1

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Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	T ²
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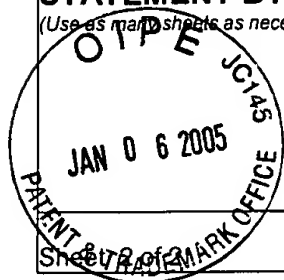
EXAMINER

DATE CONSIDERED

Substitute Disclosure Statement Form (PTO-1449)

* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached

Substitute for form 1449A/PTO
**INFORMATION DISCLOSURE
 STATEMENT BY APPLICANT**
 (Use as many sheets as necessary)



Complete if Known

Application Number	09/733,289
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Group Art Unit	2814
Examiner Name	Nguyen, DiLinh

Attorney Docket No: 884.798US1

FOREIGN PATENT DOCUMENTS

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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER

DATE CONSIDERED